CHAPTER THIRTY TWO

Semiconductor Read-Only Memories

Introduction

Diode circuits, BJT circuits, and MOSFET circuits are used to provide memory semiconductor circuits consisting of both Read-Only Memories (ROM) and Random-Access Memories (RAM) (*next chapter*).

Figure 1

© *http://computer.howstuffworks.com/rom4.htm*

ROM chips (Figure 1) contain a grid of columns and rows. But where the columns and rows intersect, ROM chips are fundamentally different from RAM chips. While RAM uses transistors to turn on or off access to a capacitor at each intersection, ROM uses a **diode** to connect the lines if the value is 1. If the value is 0, then the lines are not connected at all.

Introduction

Semiconductor IC ROMs refer to sub-circuits that are designed to store a predefined pattern of values in a binary format by encoding each logic "0" and "1" by the absence or presence of a single diode or transistor.

Entire chips can be designed as ROMs to store a program such as the boot up code and basic input/output service (BIOS) routines used by computers.

IC ROMs can be used to store operating software for appliances such as microwave ovens, washing machines

Introduction

Special types of ROMs can be programmed after fabrication (Programmable Read-Only Memory (PROM). In PROMs, a fuse is connected with a diode or a transistor. So the PROMs can be programmed by intentionally blowing the fuse of each bit that is desired to be inverted.
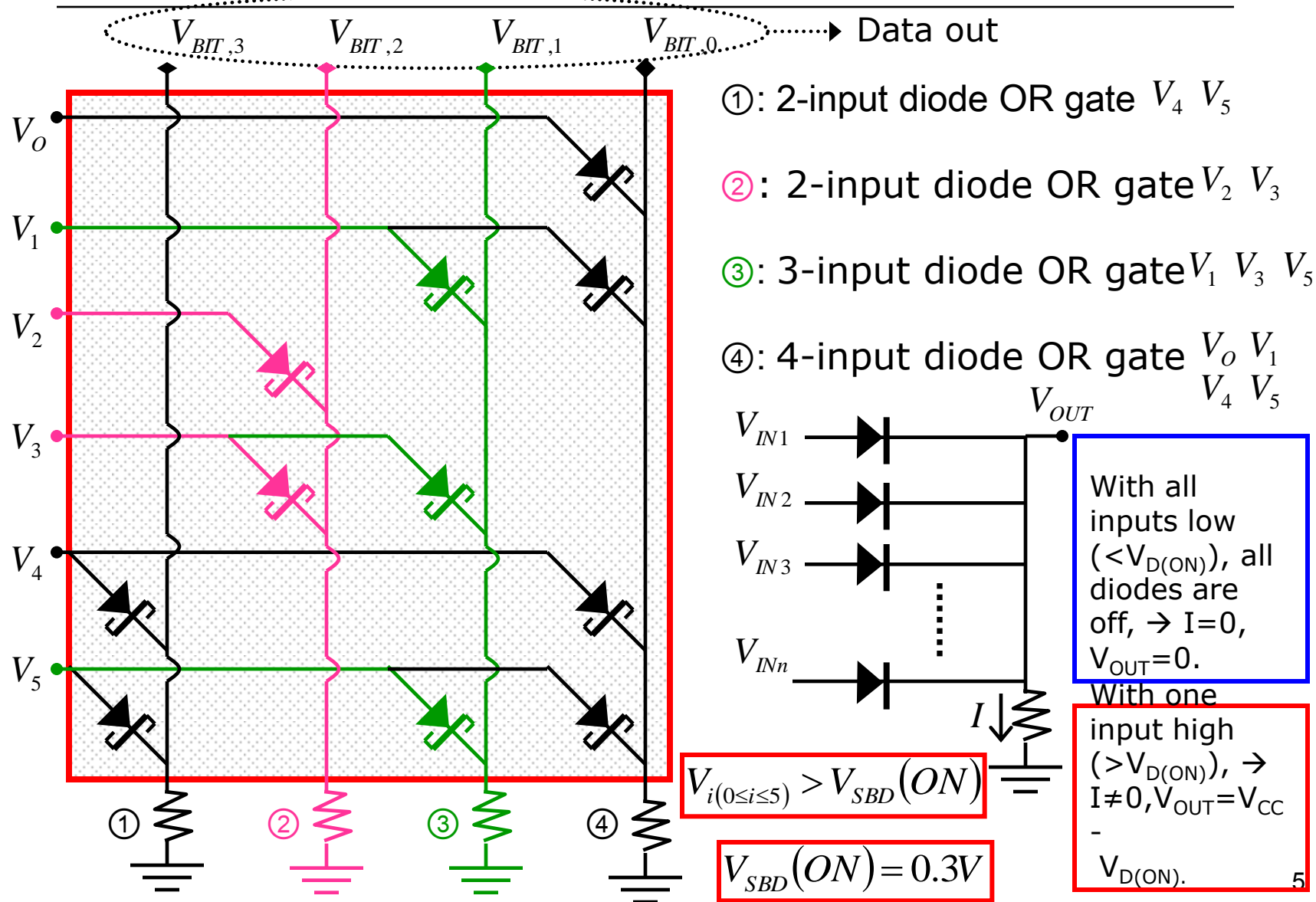
Figure 2

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PROM
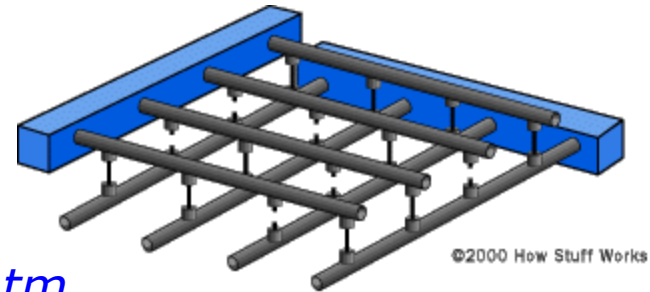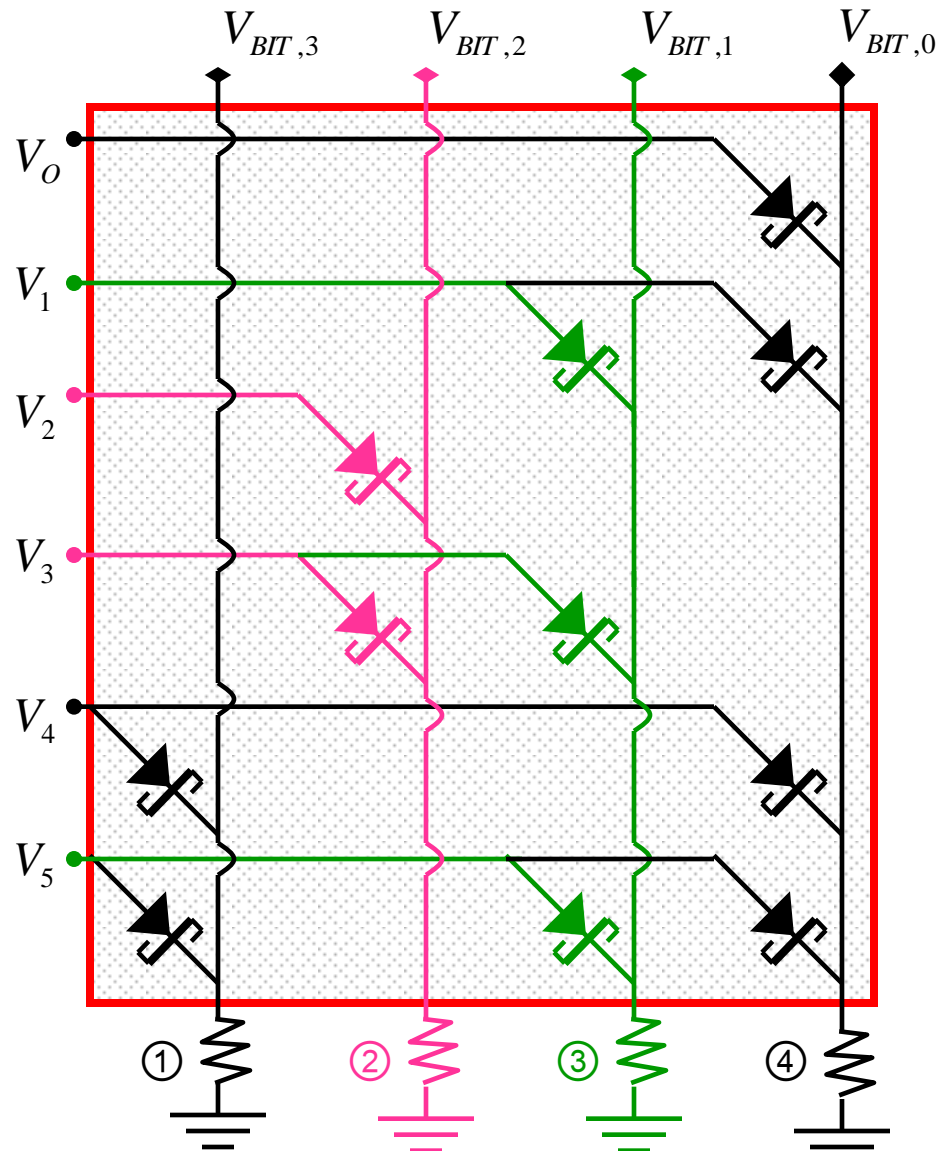
http://computer.howstuffworks.com/rom3.htm

PROM chips (Figure 2) have a grid of columns and rows just as ordinary ROMs do. The difference is that every intersection of a column and row in a PROM chip has a fuse connecting them. A charge sent through a column will pass through the fuse in a cell to a grounded row indicating a value of 1. Since all the cells have a fuse, the initial (blank) state of a PROM chip is all 1s. To change the value of a cell to 0, you use a programmer to send a specific amount of current to the cell. The higher voltage breaks the connection between the column and row by burning out the fuse. This process is known as burning the PROM.

**PROMs can only be programmed once.**

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Diode Read-Only Memories

Data out

①: 2-input diode OR gate V_4 V_5

②: 2-input diode OR gate V_2 V_3

③: 3-input diode OR gate V_1 V_3 V_5

④: 4-input diode OR gate V_O V_1 V_4 V_5

V_{OUT}

With all inputs low ($<V_{D(ON)}$), all diodes are off, → I=0, V_{OUT}=0.

With one input high ($>V_{D(ON)}$), → I≠0, V_{OUT}=V_{CC} - $V_{D(ON)}$.

$$V_{i(0 \le i \le 5)} > V_{SBD}(ON)$$

$$V_{SBD}(ON) = 0.3V$$

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Diode Read-Only Memories

□ This circuit (*Schottky diode ROM*) represents a simple four bit, six address ROM cell

□ The data out bit lines are labeled

$V_{BIT,3}$ $V_{BIT,2}$ $V_{BIT,1}$ $V_{BIT,0}$

□ In all CMOS ROM circuits, a high voltage is regarded as a **1** and a low voltage as a **0**.

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Operation of Diode ROM

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Ch. 32
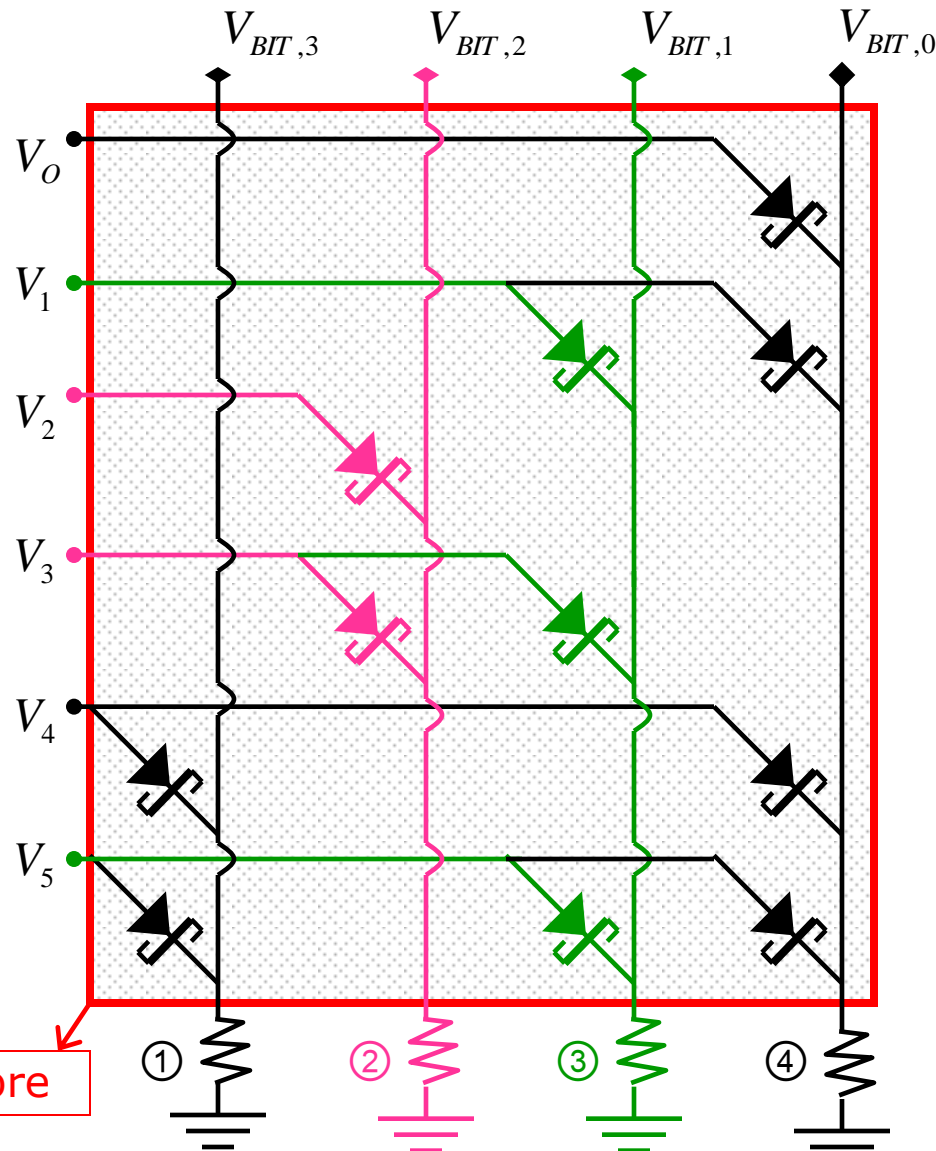
ROM Core

Only V_O is high "1"

Data Output values: **0001**

Only V_1 is high "1"

Data Output values: **0011**

Only V_2 is high "1"

Data Output values: **0100**

Only V_3 is high "1"

Data Output values: **0110**

Only V_4 is high "1"

Data Output values: **1001**

Only V_5 is high "1"

Data Output values: **1011**

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Utilization of Diode ROM Circuit

V_O

V_1

V_2

V_3

V_4

V_5

$V_{BIT,0}$

$V_{BIT,2}$

$V_{BIT,1}$

$V_{BIT,3}$
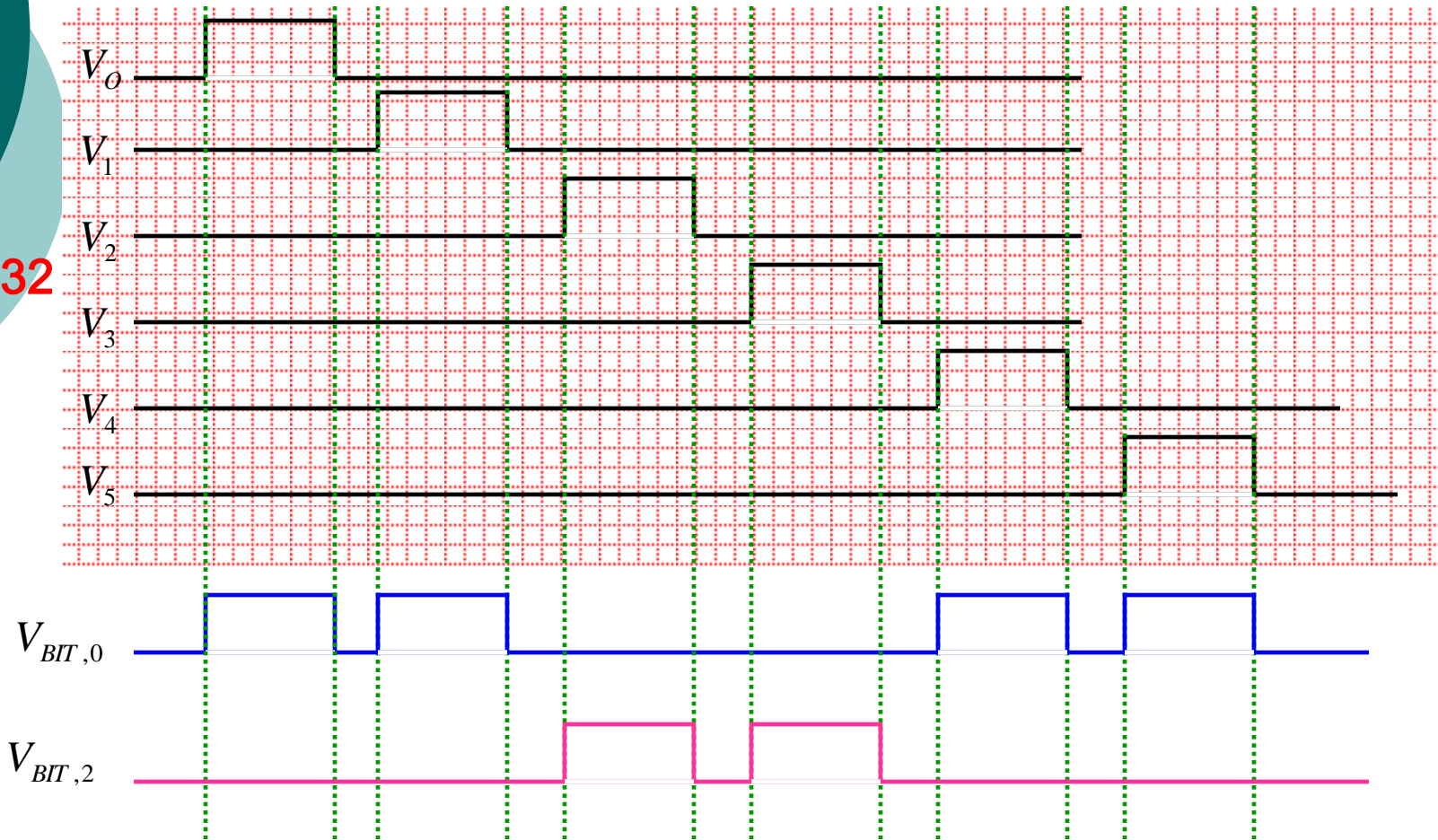
④: 4-input diode OR gate $\quad V_O \quad V_1$
$\qquad\qquad\qquad\qquad\qquad\qquad V_4 \quad V_5$

②: 2-input diode OR gate $V_2 \quad V_3$

Design of Diode ROM Circuit

Ch. **32**

❑ Diodes are to be placed between <u>input row lines</u> and data <u>out column lines</u> where logic <u>high</u> bits are desired.

❑ An absence of a diode stores logic low
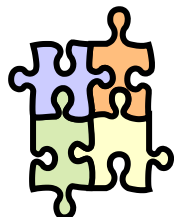
○ Example

Design a Shottky diode ROM circuit that has five data out bits and stores the six decimal (basis 10) values 21,14,1,10, 13, and 18

○ Solution

The diode ROM circuit stores binary values (decimal→ binary)

$(21)_{10}= 16+4+1= 2^4+2^2+2^0 →(\mathbf{10101})_2$	$(14)_{10}= 8+4+2= 2^3+2^2+2^1 →(\mathbf{01110})_2$

$(1)_{10}= 1= 2^0 →(\mathbf{00001})_2$	$(10)_{10}= 8+2= 2^3+2^1 →(\mathbf{01010})_2$

$(13)_{10}= 8+4+1= 2^3+2^2+2^0 →(\mathbf{01101})_2$	$(18)_{10}= 16+2= 2^4+2^1→(\mathbf{10010})_2$
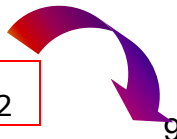
○ Solution

V0→(10101)$_2$
V1→(01110)$_2$
V2→(00001)$_2$
V3→(01010)$_2$
V4→(01101)$_2$
V5→(10010)$_2$

BJT Read-Only Memories

N-input transistor OR gate
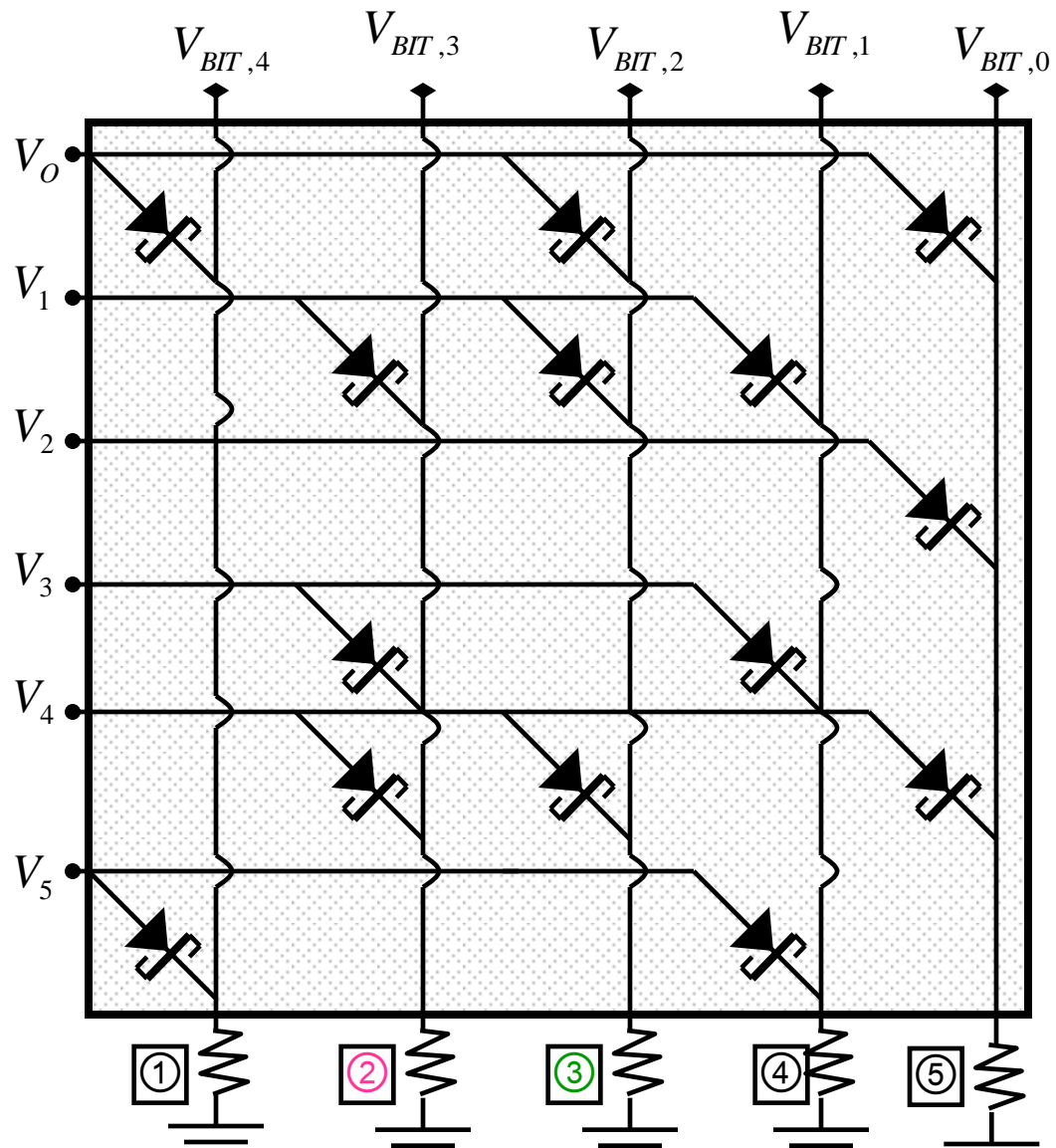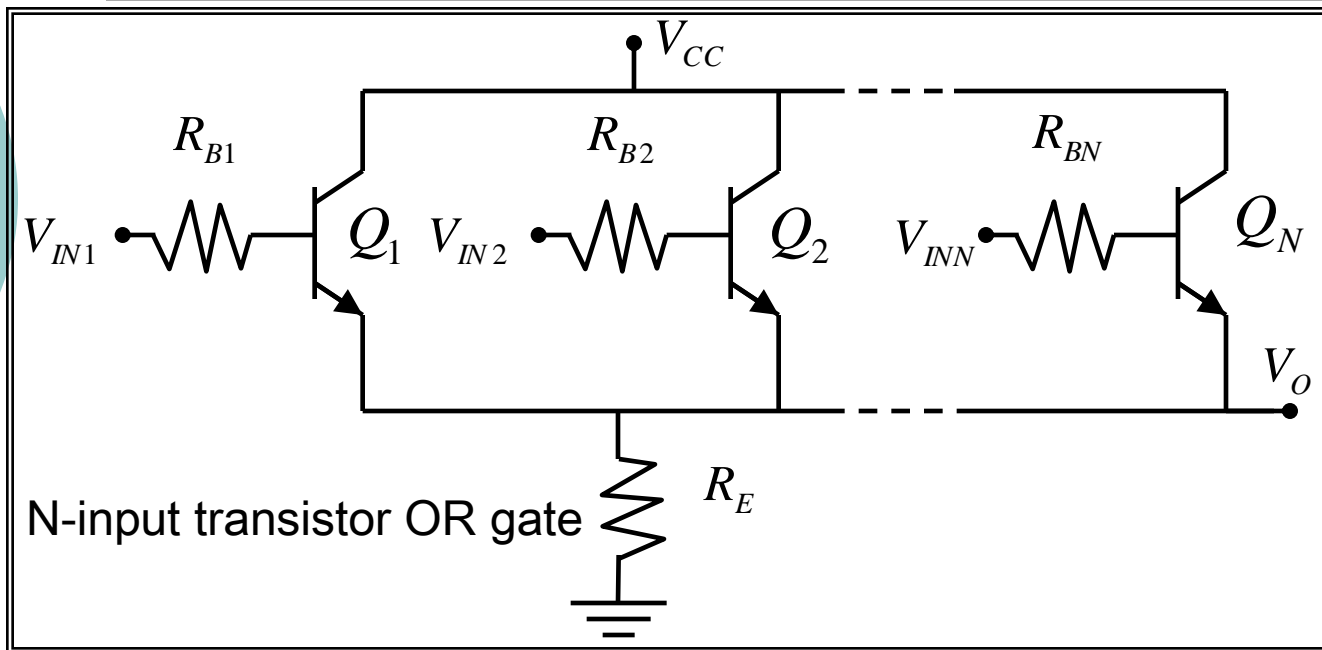
❑ The *Schottky diodes are replaced by BJTs*

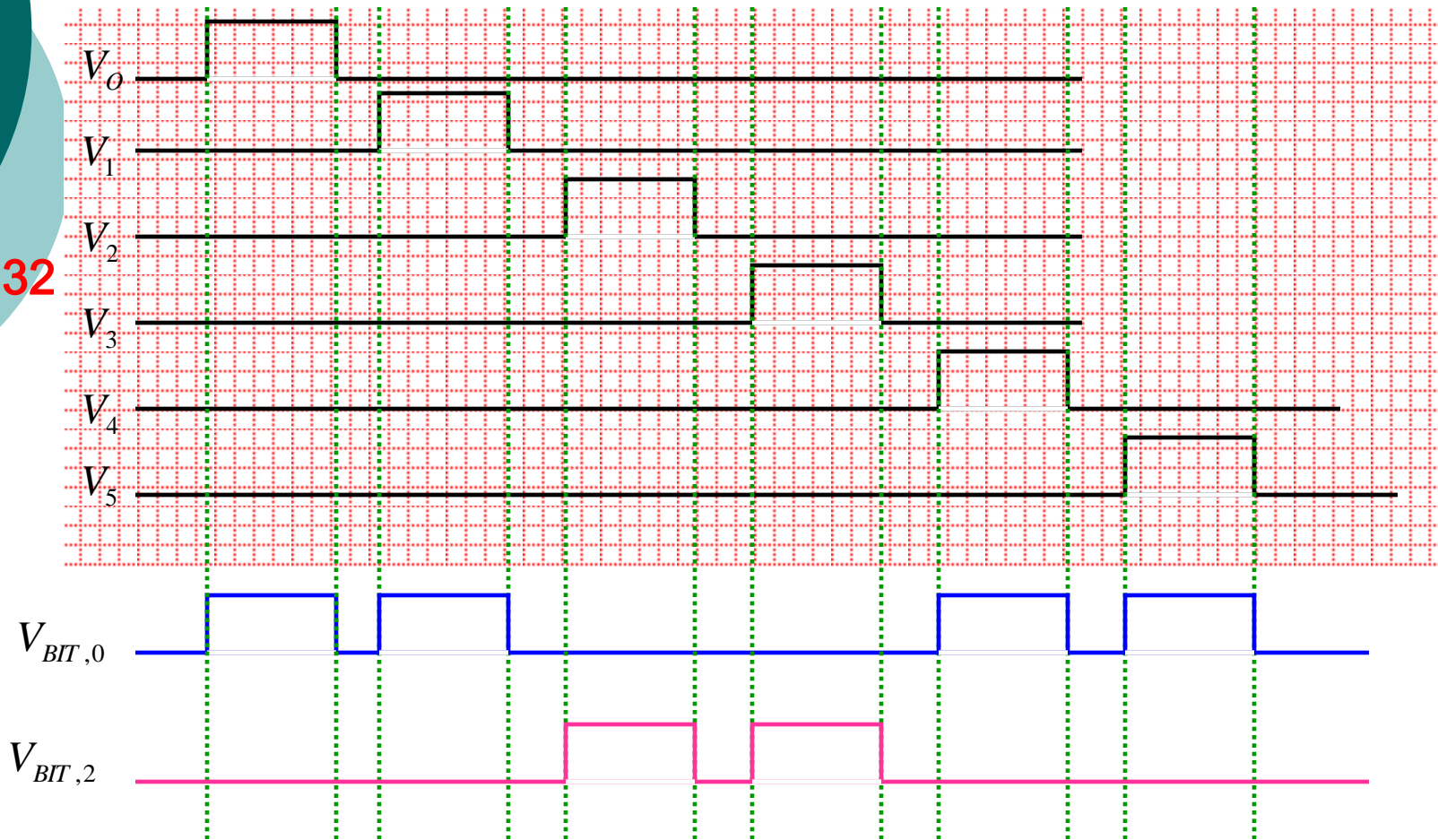N-input transistor OR gate

BJT Read-Only Memories

Ch. **32**
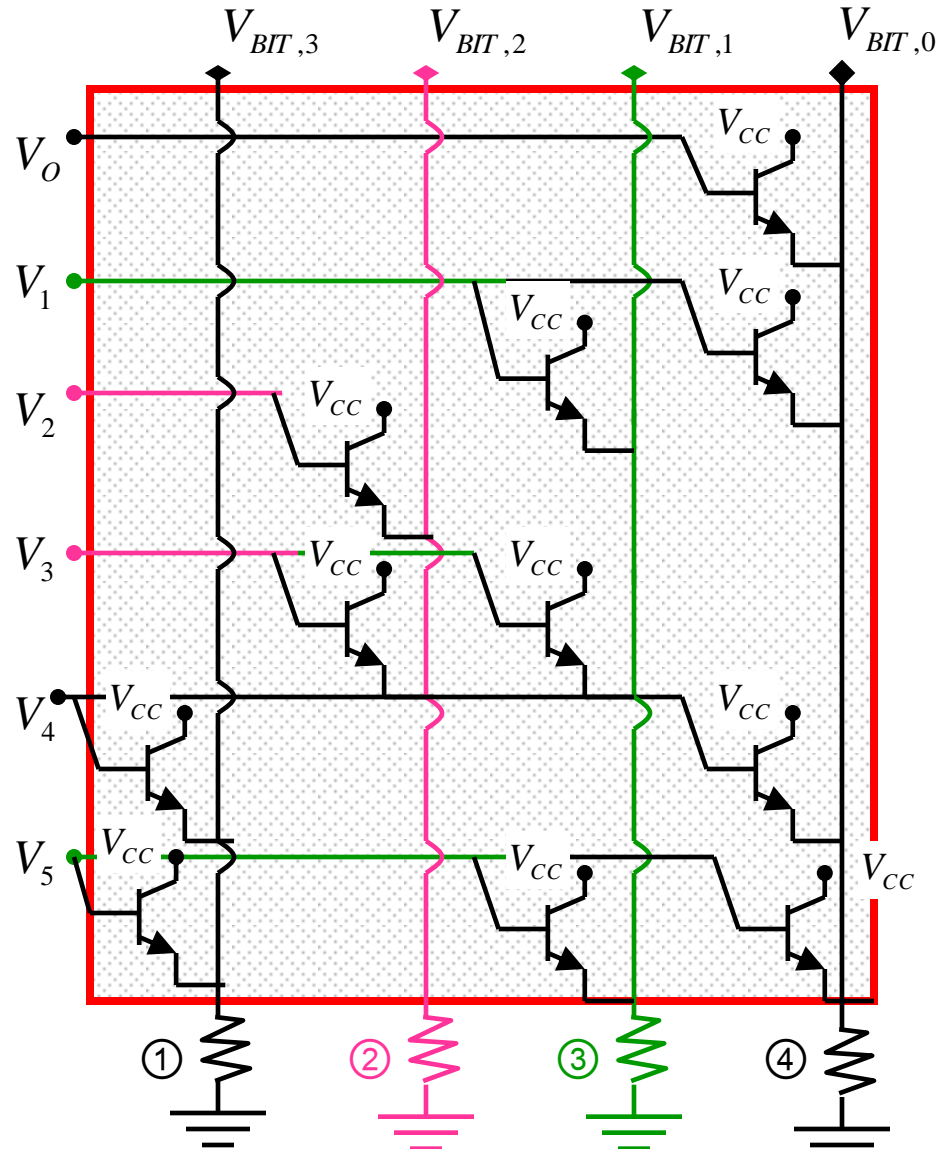
□ This circuit (*BJT ROM*) represents a simple four bit, six address ROM cell

□ The data out bit lines are labeled

$V_{BIT,3}$ $\quad$ $V_{BIT,2}$ $\quad$ $V_{BIT,1}$ $\quad$ $V_{BIT,0}$
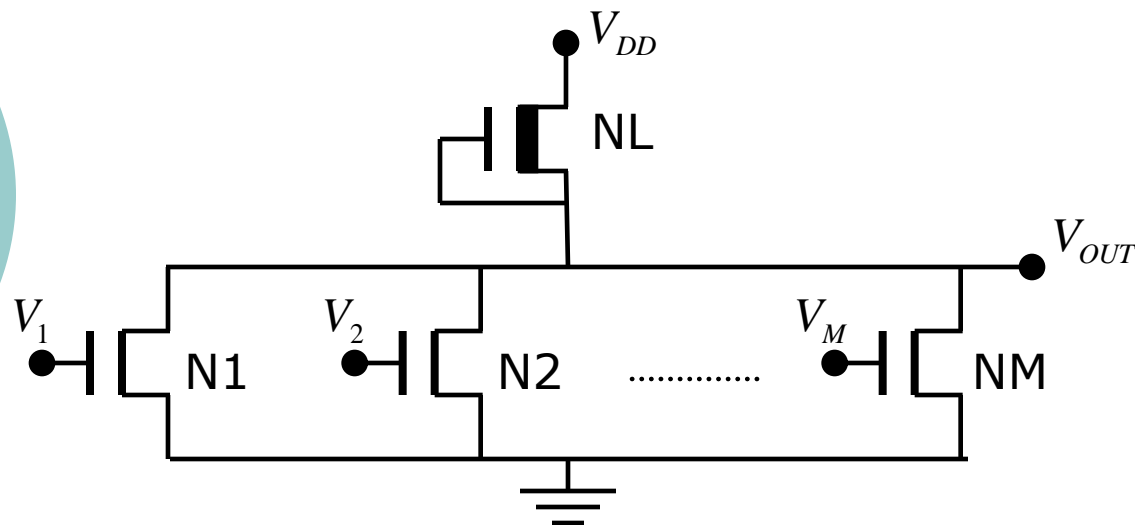
Utilization of BJT ROM Circuit

Ch. **32**

V_O

V_1

V_2

V_3

V_4

V_5

$V_{BIT,0}$

$V_{BIT,2}$

$V_{BIT,1}$

$V_{BIT,3}$

④: 4-input BJT OR gate V_O V_1
                                  V_4 V_5

②: 2-input BJT OR gate V_2 V_3

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NMOS Read-Only Memories

$$V_{OH} = V_{DD} - V_L(OH)$$

$$V_L(OH) = 0$$

❑ The NOR gate with at least one high-input has a low output logic level.

❑ The NOR gate with all its inputs are low has a high output logic level.

For all NMOS logic families except the saturated enhancement-only loaded NMOS

$$V_{OL}(E-D\ loaded) = \frac{k_L V_{T,L}^2}{2k_O(V_{DD}-V_{T,O})}$$

$$k_O = \mu_n C_{ox}\left(\frac{W_{O,1}}{L_{O,1}} + \frac{W_{O,2}}{L_{O,2}} + \cdots \frac{W_{O,M}}{L_{O,M}}\right)$$

Transconductance parameter

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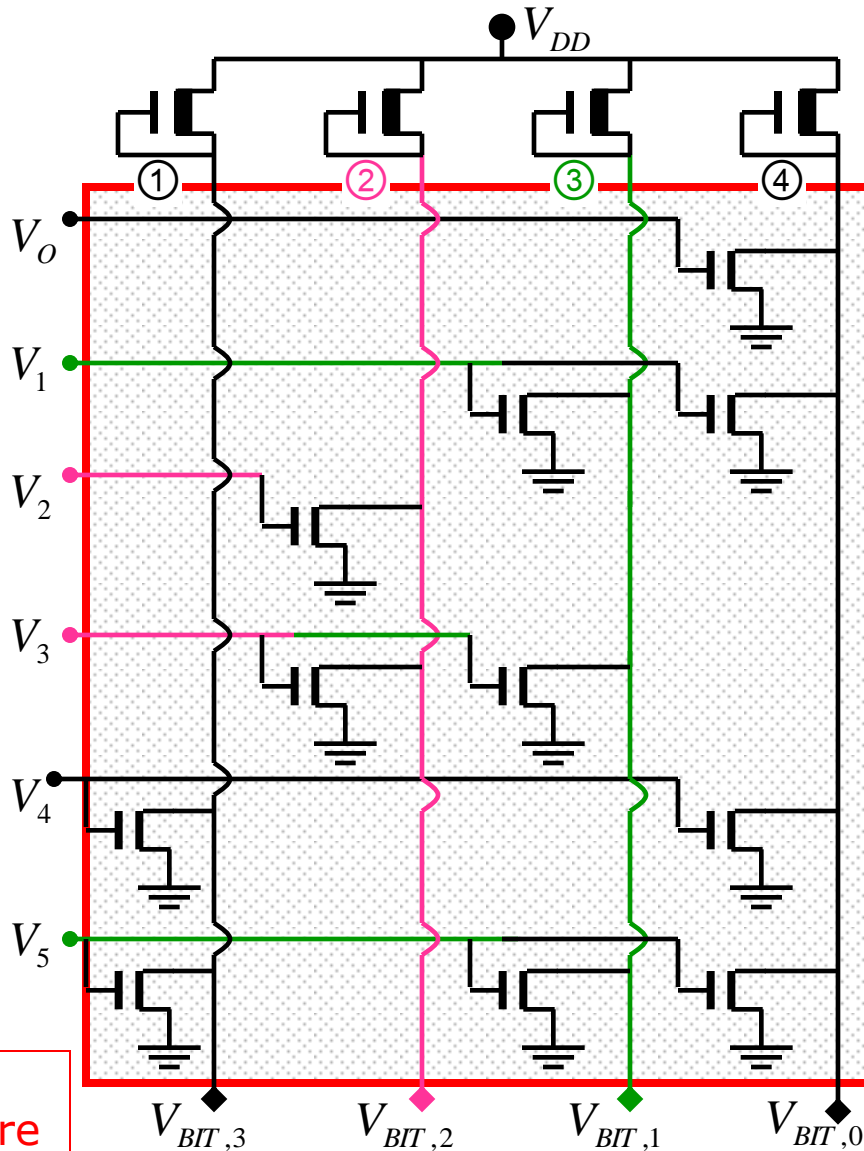# NMOS Read-Only Memories

Ch. 32
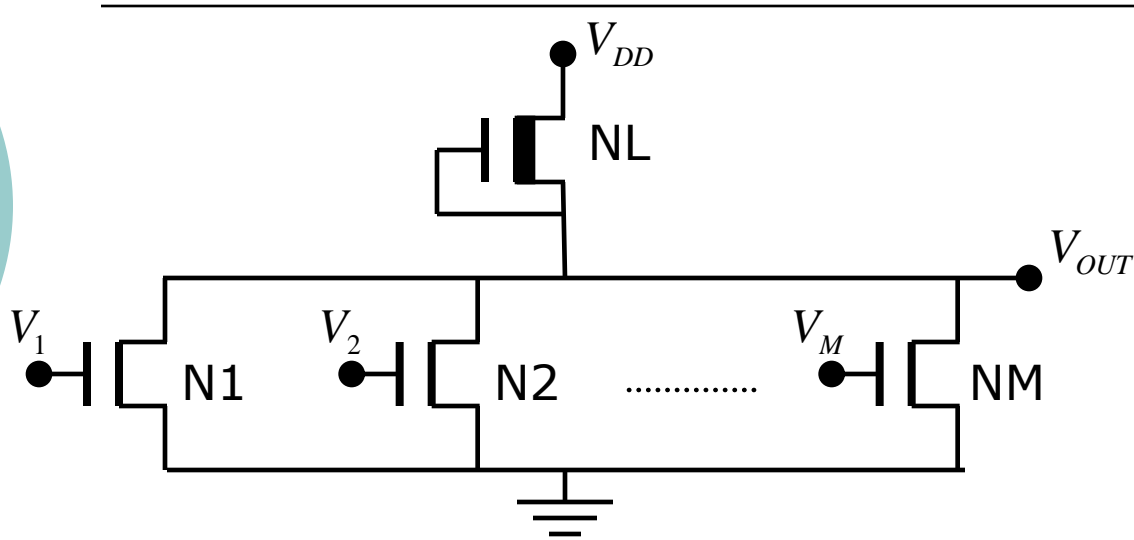
M-input NMOS NOR gate
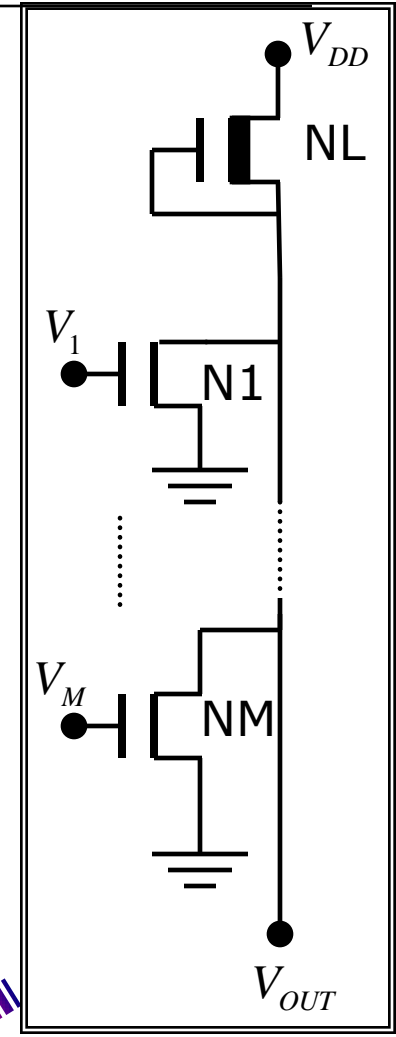
Each enhancement NMOS provides an output pull-down path

The single depletion NMOS provides an output pull-up path

$$V_{GS,L} = 0 > V_{TN,L} \Rightarrow ON$$

Basis of NMOS ROM cell

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Operation of NMOS NOR ROM Cell

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NMOS ROM Core

❑ This circuit (*NMOS ROM*) represents a simple four bit, six address ROM cell

❑ The data out bit lines are labeled

$$V_{BIT,3} \quad V_{BIT,2} \quad V_{BIT,1} \quad V_{BIT,0}$$

❑ The NOR gate with at least one high-input has a low output logic level.

❑ The NOR gate with all its inputs are low has a high output logic level.

Data out
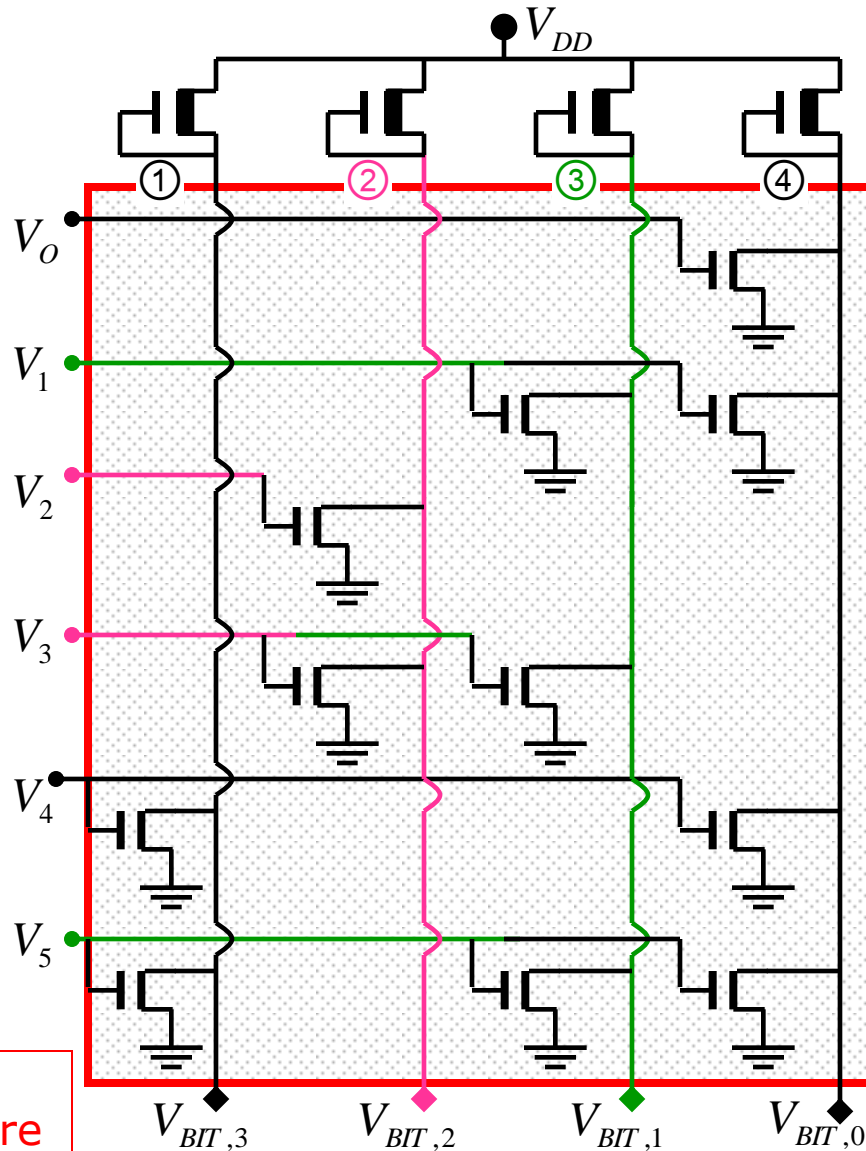
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Operation of NMOS NOR ROM Cell

Only V_O is high "1"

Data Output values: **1110**

Only V_1 is high "1"

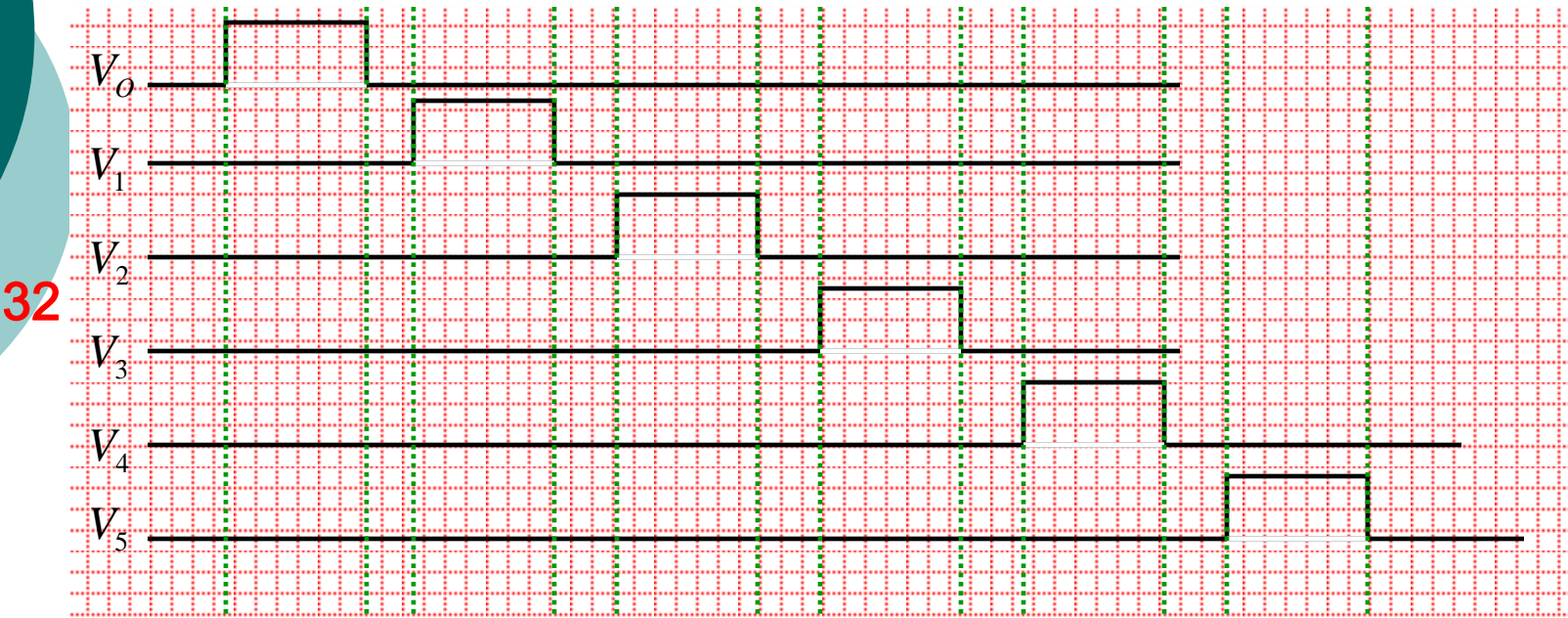Data Output values: **1100**

Only V_2 is high "1"

Data Output values: **1011**

Only V_3 is high "1"

Data Output values: **1001**

Only V_4 is high "1"

Data Output values: **0110**

Only V_5 is high "1"

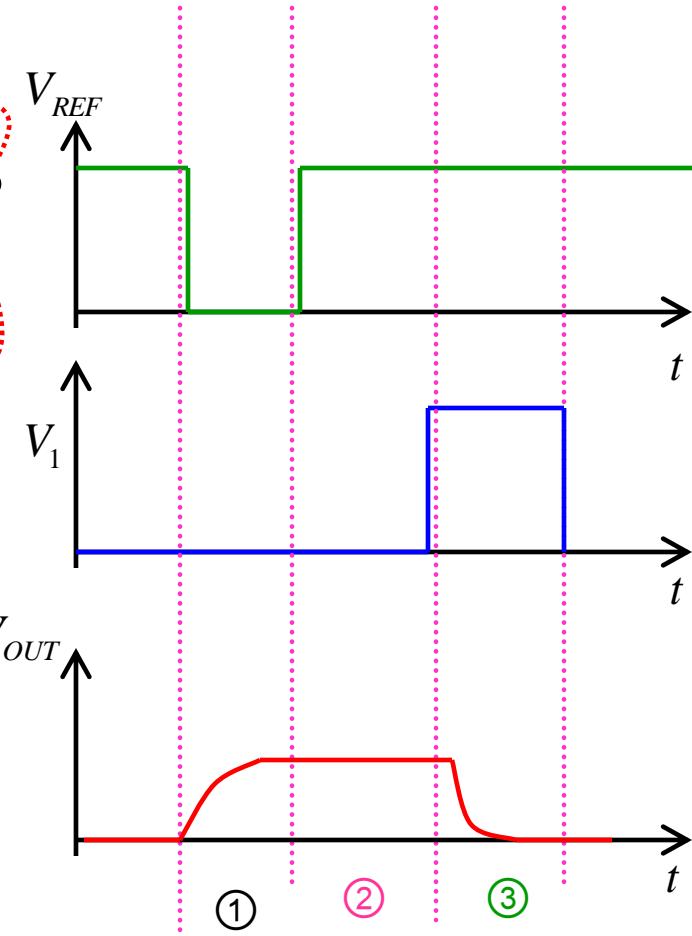Data Output values: **0100**

Utilization of NMOS NOR ROM Cell

V_O
V_1
V_2
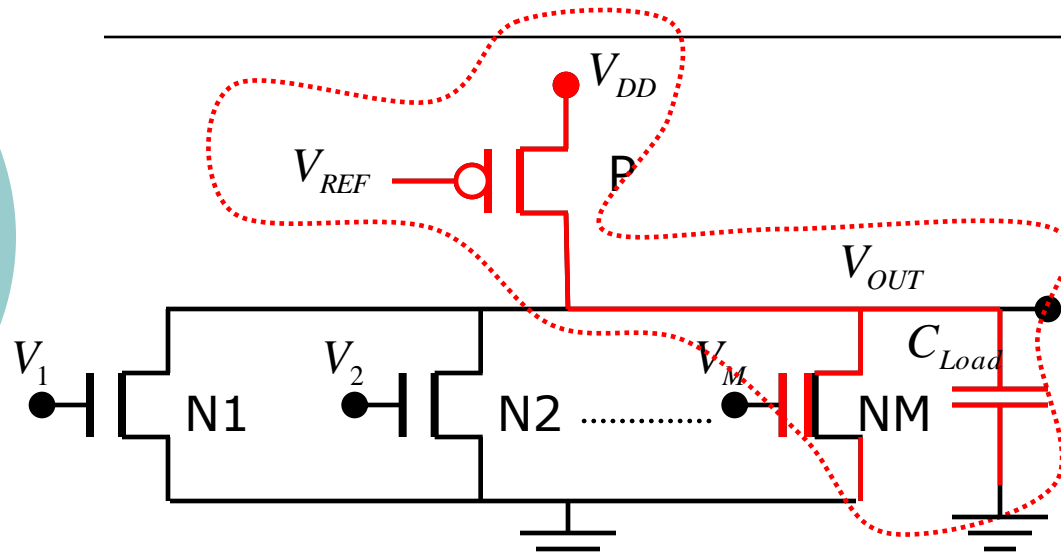V_3
V_4
V_5

$V_{BIT,0}$

$V_{BIT,2}$

$V_{BIT,1}$

$V_{BIT,3}$

④: 4-input NMOS NOR gate V_O V_1 V_4 V_5
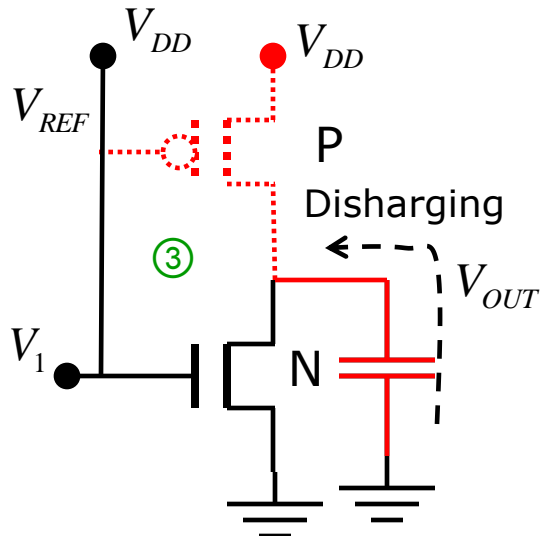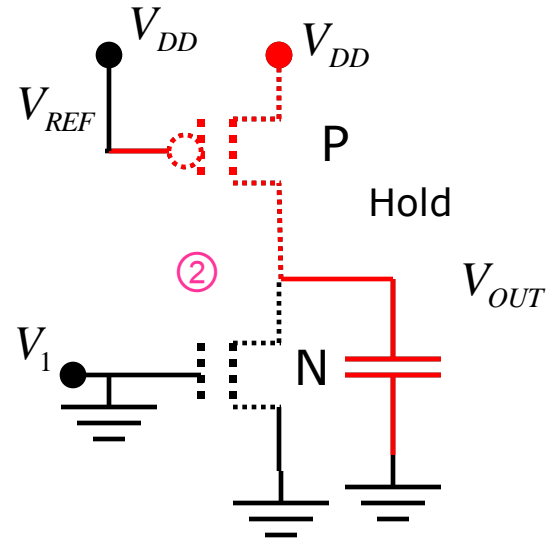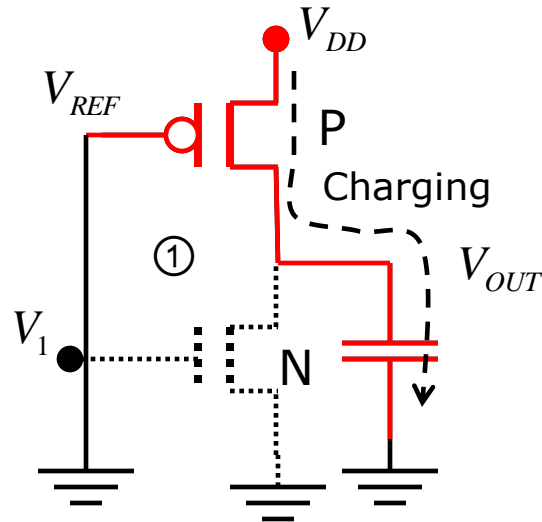
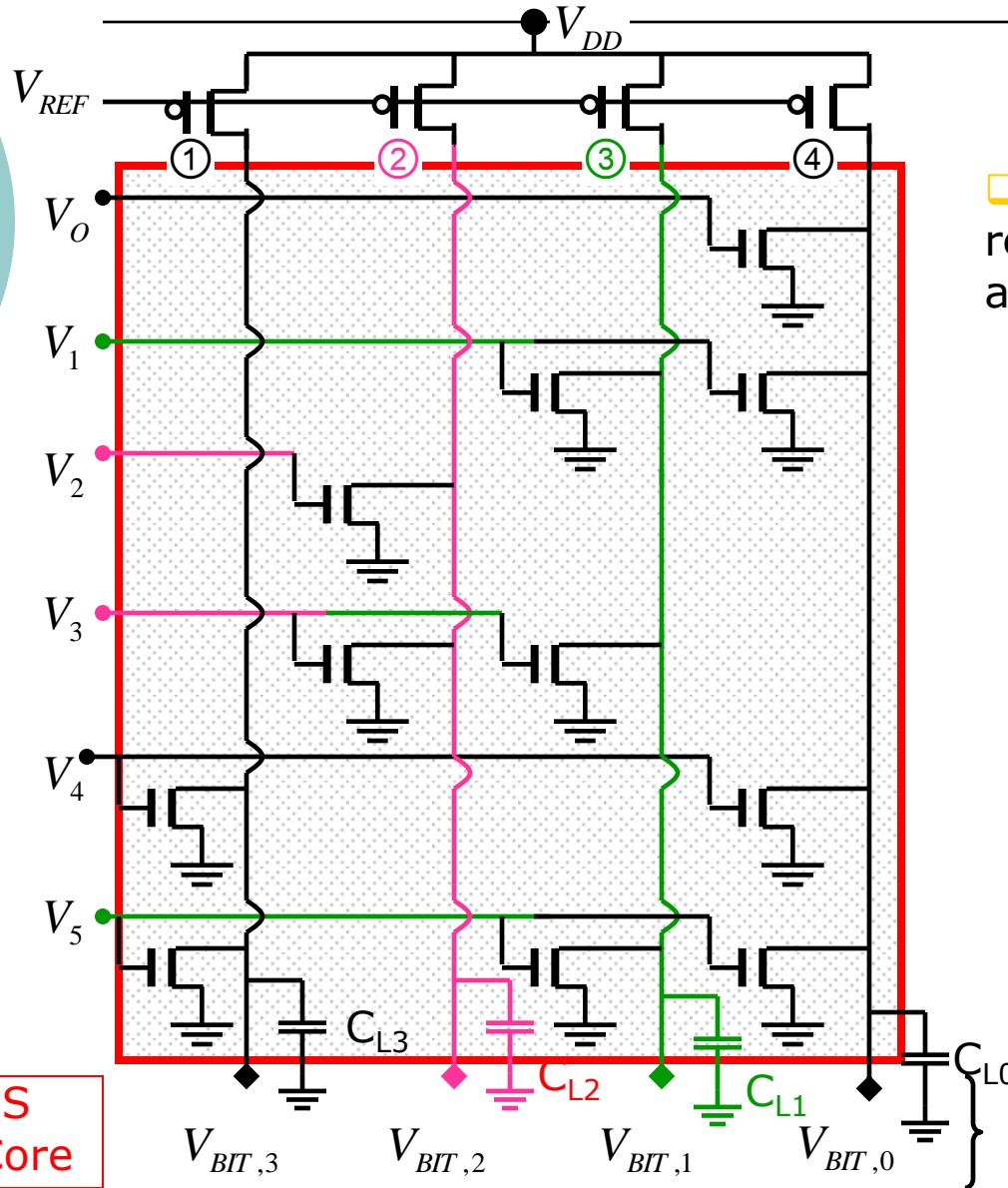②: 2-input NMOS NOR gate V_2 V_3

CMOS Read-Only Memories

Ch. 32

☐ Unlike the previous ROMs, the CMOS output depends on the storage of charge in the load capacitance on each bit output line.

☐ To have a zero power consumption

☐ The CMOS ROMs dissipate power only during switching.

CMOS Read-Only Memories
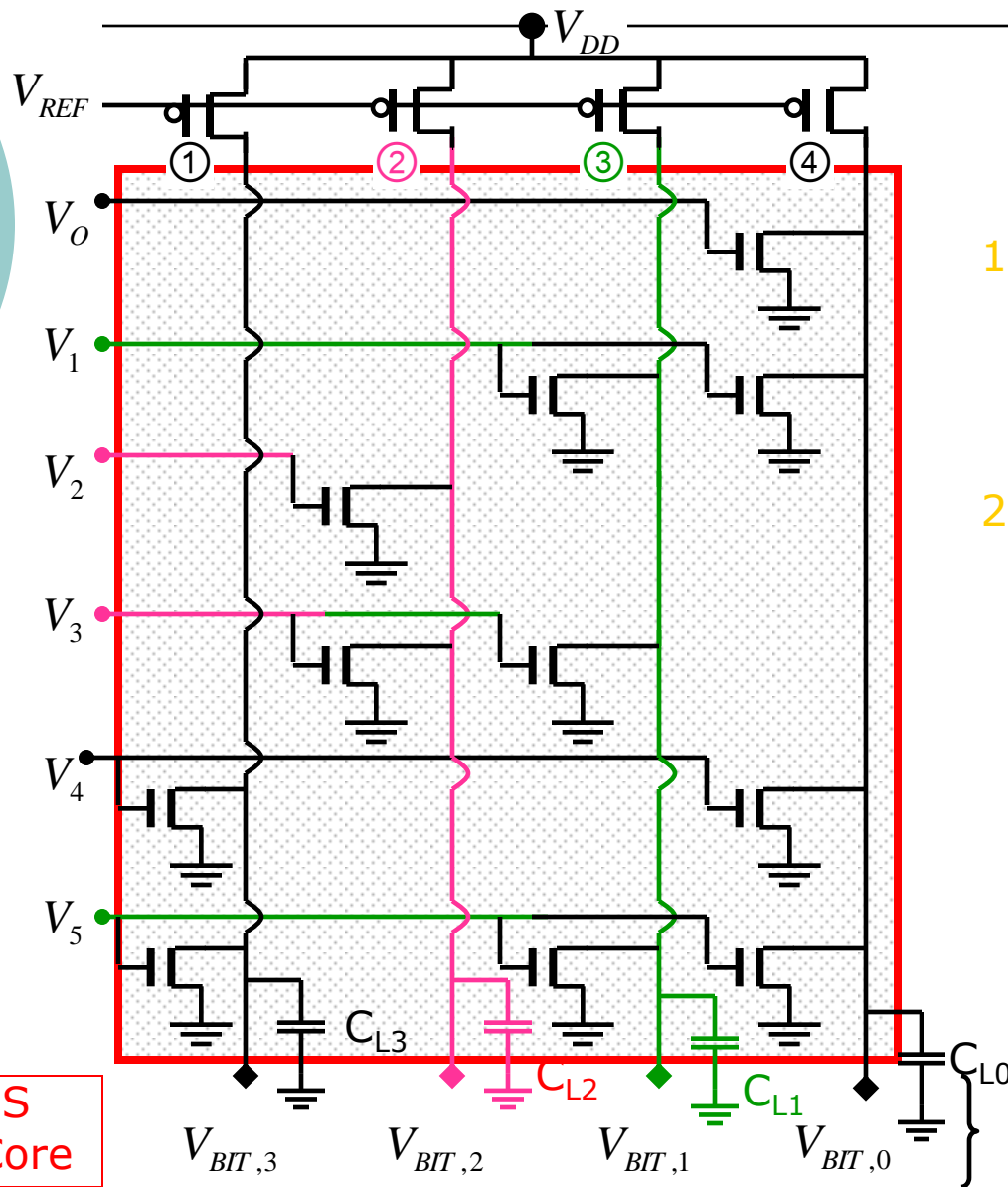
Operation of CMOS ROM Cell

❏ This circuit (*CMOS ROM*) represents a simple four bit, six address ROM cell

❏ The data out bit lines are labeled

$$V_{BIT,3} \quad V_{BIT,2} \quad V_{BIT,1} \quad V_{BIT,0}$$

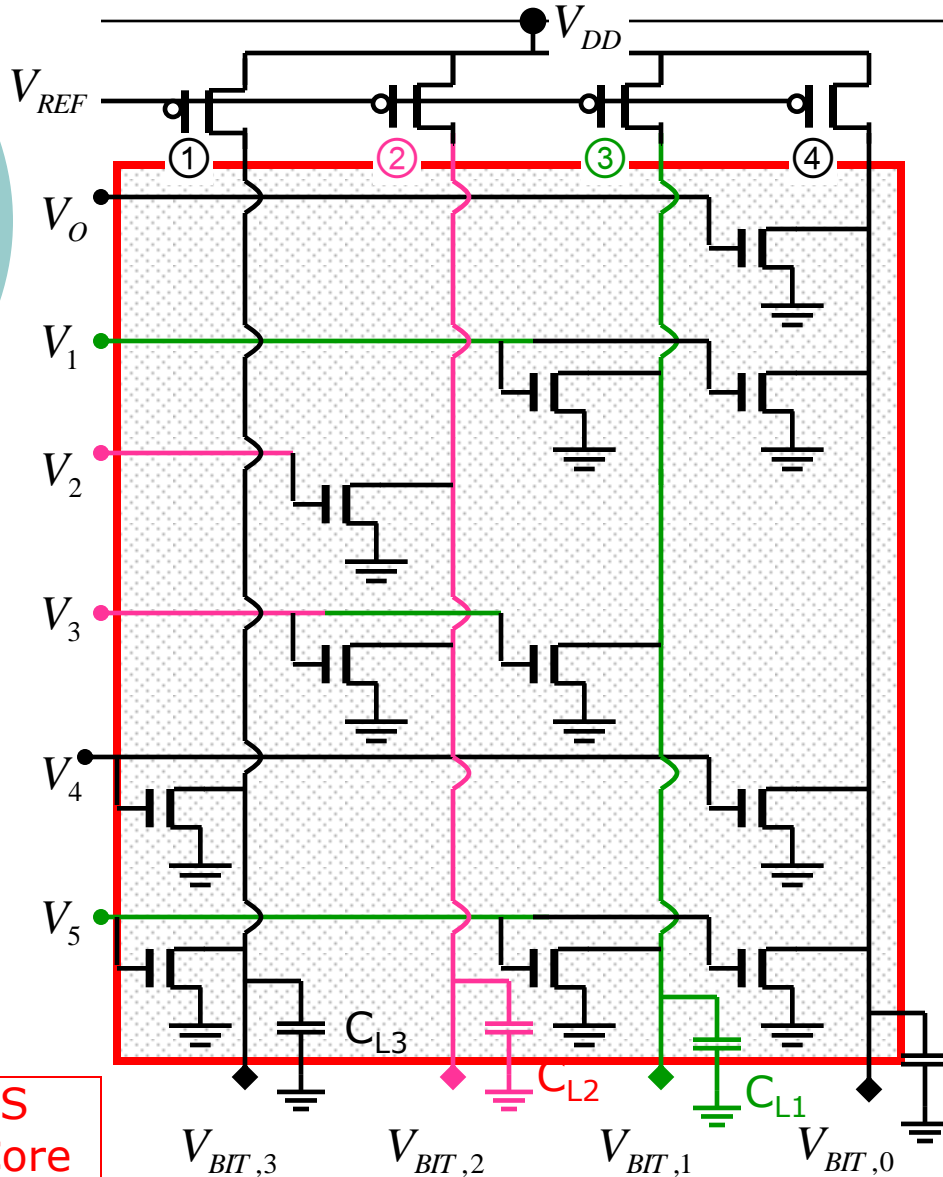# Operation of CMOS ROM Cell Precharging Holding Capacitances

1. The V_{REF} must be temporarily low while the all the six address inputs are held low.

2. These voltages charge the holding capacitance of each of the four bit output lines

3. After all the holding capacitances have been charged to $V_{OH}=V_{DD}$, the V_{REF} is brought to high.

Operation of CMOS ROM Cell Precharging Holding Capacitances

V_{REF} (Low)

Only V_O is high "1"

Data Output values: **1110**

Only V_1 is high "1"

Data Output values: **1100**

Only V_2 is high "1"
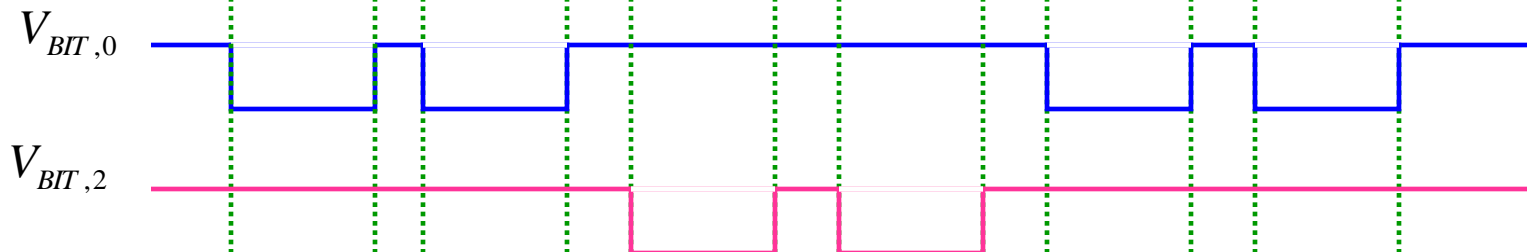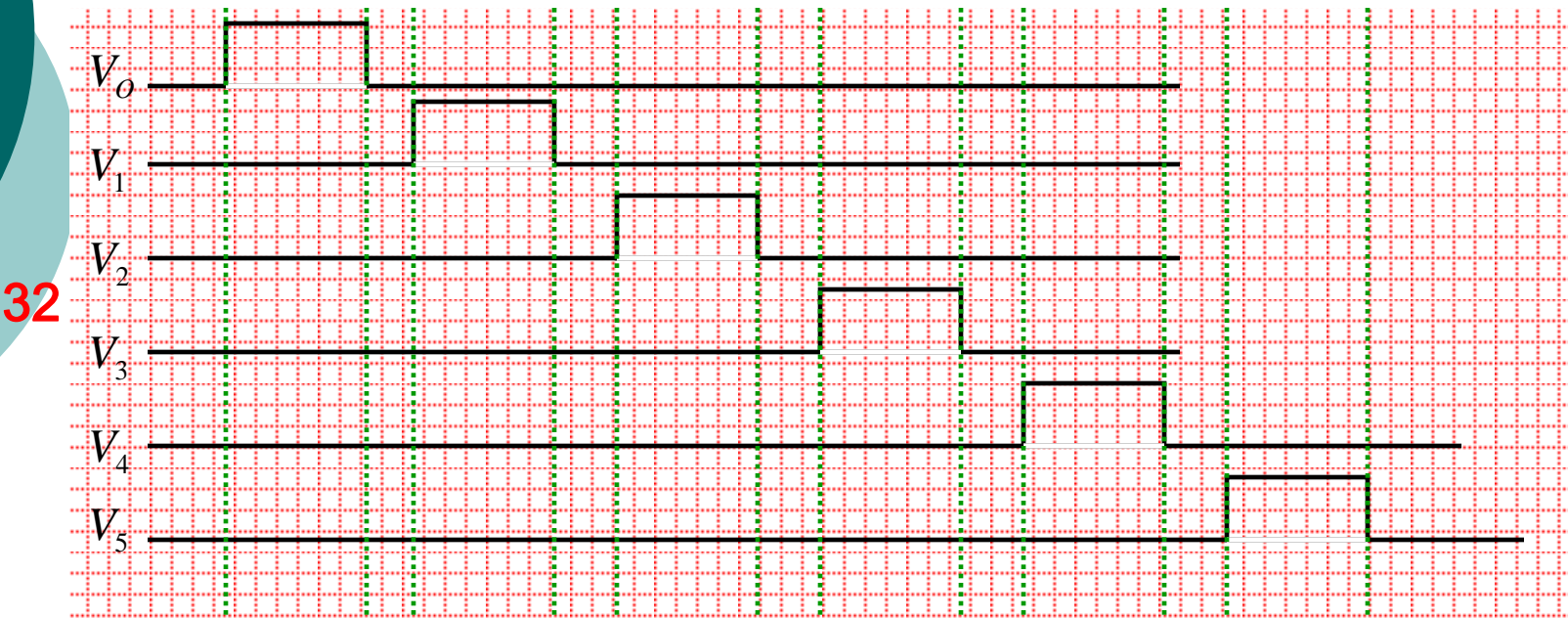
Data Output values: **1011**

Only V_3 is high "1"

Data Output values: **1001**

Only V_4 is high "1"

Data Output values: **0110**

Only V_5 is high "1"

Data Output values: **0100**

CMOS ROM Core

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Ch. **32**

Utilization of CMOS ROM Cell

Ch. 32

V_O

V_1

V_2

V_3

V_4

V_5

$V_{BIT,0}$

$V_{BIT,2}$

$V_{BIT,1}$

$V_{BIT,3}$

④: 4-input CMOS gate

②: 2-input CMOS gate

V_O V_1
V_4 V_5

V_2 V_3

Ch. **32**

- HW #14:Solve Problems: 32.6, 32.22, 32.27, and 32.28